ABSTRACT

A wire bonding method comprising: disposing a plurality of leads (20) aligned in an imaginary plane (P) around the periphery of a semiconductor chip (10) having a plurality of electrodes (12) aligned on an imaginary straight line (L1); bonding wires (30) to the electrodes (12); bending the wires (30) toward the leads (20) as viewed from a direction perpendicular to the imaginary plane (P); and bonding the wires (30) to the leads (20).